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Abstract

Method for the production of components for electronic apparatuses from a sheet-like substrate material, which has through-holes and indentations on at least one surface, an intermediate layer on at least one surface of the substrate material, and a metal foil adhering to said layer, comprising the steps (a) coating of a sheet-like substrate with a composition forming the intermediate layer, (b) application of the metal foil to the coating and (c) bonding of the parts by pressure and heating. The method is characterized by the use of a liquid, solvent-containing and heat-curable two-component system comprising at least one curing agent and at least one curable compound, which system is applied as the layer to at least one surface of a substrate material and then dried. A metal foil is then laminated with the resulting solid and dry layer under pressure and at elevated temperature and the layer is cured. Particularly preferably, circuit boards are produced by the method according to the invention.

(Figure 3)

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